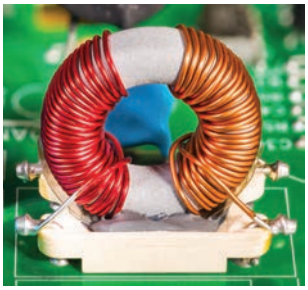
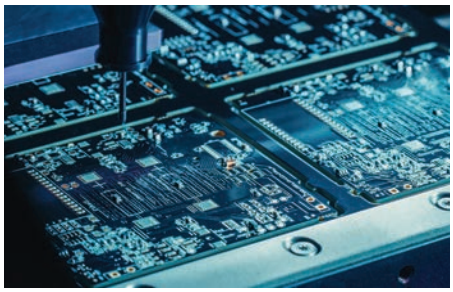
Automotive Products



• Low Stress

• Structural Adhesives



• Electronic Assembly

PRODUCT	DESCRIPTION	VISCOSITY HIGH SHEAR RATE (cP)	CURE SCHEDULE
	Low Stress		
703-60	Designed as a high flexibility adhesive and sealant. It was designed for glass-to-glass, metal, and ceramic bonding where flexibility at -40ºF temperature are critical	Paste	6 min @ 177ºC
769-6HF R&D	Meets IEC 61249-2-21 as a Halogen-Free material. Similar properties to 703-60, designed for European automotive standards	21,000	20 min @ 150ºC
	Structural		
400-76-1	Heat curable epoxy adhesive. Outstanding thermal shock resistance and extremely high adhesion. Exceptional thermal stability and resistance to water, humidity and solvents	80,000	20 min @ 150ºC
502-09	High performance adhesive with exceptional high temperature properties. Induction curable or standard convection cure oven resulting in a very high glass transition temperature	Paste	30 min @ 160ºC
505-96	A high performance paste adhesive with exceptional high temperature properties. Cures rapidly in a standard convection cure oven resulting in a very high glass transition temperature	170,000	20 min @ 135ºC
NEW 506-12	Heat curable non-sag epoxy adhesive. Excellent adhesion strength to metals (up to 5,000+ PSI) and strong bonds to ceramics. Exceptional thermal stability and resistance to water, humidity and solvents	Paste	15 min @ 160ºC
702-98	Heat curable non-sag epoxy adhesive. Strong bonds to metals and ceramics. Exceptional thermal stability and resistance to water, humidity and solvents	Paste	15 min @ 150ºC
	Electronic		
505-62	Heat curable epoxy, which forms strong bonds to metals and ceramics. Upon cure has exceptional thermal stability and resistance to water, humidity and solvents	50,000	10 min @ 140ºC
505-88	Heat curable epoxy, which forms strong bonds to metals and ceramics. Upon cure has exceptional thermal stability and resistance to water, humidity and solvents	45,000	10 min @ 140ºC
629-3A/B	Black, epoxy/acid anhydride encapsulating compound. Upon cure develops excellent adhesion to a variety of substrates with a low coefficient of thermal expansion (CTE)	2,500	60 min @ 150ºC
XNR3625(D)	Heat curable epoxy adhesive, which forms strong bonds to metals, ceramics, and some plastics. Upon cure has exceptional thermal stability and resistance to water, humidity and solvents	70,000	60 min @ 120ºC